Materials Declaration

Package	PLCC
Body Size	9 x 9
LeadCount	20
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	2	1.01 E-02	17255
SiO2 Filler	85	4.30 E-01	733354
Epoxy Resin	6.4	3.24 E-02	55217
Phenol Resin	6.4	3.24 E-02	55217
Carbon Black	0.2	1.01 E-03	1726

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	,2	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	9.30 E-02	158663
Zr	0.1	9.31 E-05	159

Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	6.43 E-04	1096

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.18 E-02	20173

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.01 E-03	1714

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.64 E-03	7908

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.01 E-04	684
Ag Filler	75	1.20 E-03	2051

Package Totals

Weight (g)	PPM
5.86 E-01	1000000

AMK-P-J

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to
any inaccuracy of such information.

ADI Proprietary

06/03/05

Materials Declaration

Package	PLCC
Body Size	9 x 9
LeadCount	20
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	16	7.28 E-02	128175
SiO2 Filler	72	3.28 E-01	576785
Phenol Novolac	8	3.64 E-02	64087
Antimony_Sb2O3	2.2	1.00 E-02	17624
Brominated Resin	1.6	7.28 E-03	12817
Carbon Black	0.2	9.11 E-04	1602

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	9.30 E-02	163690
Zr	0.1	9.31 E-05	164

Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	6.43 E-04	1131

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.01 E-02	17690
Pb	15	1.77 E-03	3122

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.01 E-03	1769

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	4.64 E-03	8158

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.53 E-04	797
Ag Filler	75	1.36 E-03	2390

Package Totals

Weight (g)	PPM
5.68 E-01	1000000

AMK-P-A

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